

What is claimed is:

1 1. A method for bonding an integrated circuit device
2 to a glass substrate comprising:

3 placing a protecting circuit, connecting with an
4 external circuit, on the glass substrate;

5 providing a melting device with a first laser device
6 and a second laser device;

7 melting a predetermined portion of the protecting
8 circuit by the first laser device emitting laser light
9 with short wavelength, and then melting a predetermined
10 portion of the glass substrate by the second laser device
11 emitting laser light with long wavelength; and

12 bonding the integrated circuit device on the glass
13 substrate.

1 2. The method as claimed in claim 1, wherein the
2 integrated circuit device comprises a driver circuit, a
3 connecting wire, and a main substrate, and the connecting
4 wire is in contact with the predetermined portion, melted
5 by the melting device, of the glass substrate when the
6 integrated circuit device is bonded to the glass
7 substrate.

1 3. The method as claimed in claim 2, wherein the
2 connecting wire is bonded to the protecting circuit of
3 the glass substrate via an adhesive and a plurality of
4 conductive particles.

1 4. The method as claimed in claim 1, wherein the
2 predetermined portion of the glass substrate is located
3 at edges of the glass substrate.